



I Mumban	Hits	Search Text	DB	Time stamp
L Number	760	capillary and wire and bond\$ and coin\$ and @ad<20010104	USPAT;	2003/09/17 17:07
	,00	capitally and wife and bonds and coms and wad 20010101	US-PGPUB;	2000/03/17 17/07
1			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	
2 .	252	(capillary and wire and bond\$ and coin\$ and @ad<20010104) and	USPAT;	2003/09/17 16:40
		semiconductor	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
3	162	((capillary and wire and bond\$ and coin\$ and @ad<20010104) and	USPAT;	2003/09/17 16:41
		semiconductor) and coat\$	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1.	20	((there are devices and boards and asias and God 20010104) and	IBM_TDB USPAT;	2003/09/17 16:41
4   1	. 29	((capillary and wire and bond\$ and coin\$ and @ad<20010104) and semiconductor) and (coat\$ near4 wire)	US-PGPUB;	2003/09/17 10.41
		semiconductor) and (coats near4 wite)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	92	capillary and wire and bond\$ and (coin coined coining) and	USPAT;	2003/09/17 17:08
	, -	@ad<20010104	US-PGPUB;	
		O	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
6	41	(capillary and wire and bond\$ and (coin coined coining) and	USPAT;	2003/09/17 17:24
		@ad<20010104) and semiconductor	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	2003/09/17 17:25
7	516	(wave adj solder\$4) and @ad<20010104 and semiconductor	USPAT; US-PGPUB;	2003/09/17 17:23
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
8	65	((wave adj solder\$4) and @ad<20010104 and semiconductor) and core	USPĀT;	2003/09/17 17:25
	05	((mare adj soldout ) and Care a	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1			IBM_TDB	
9	56		USPAT;	2003/09/17 17:25
1		and bond\$4	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	70	ibm.as. and (flip adj chip) and @ad<20010104	IBM_TDB USPAT;	2003/09/17 16:38
-	79	iom.as. and (mp adj cmp) and @ad~20010104	US-PGPUB;	2303/07/17 10:30
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	,
_	798	(flip adj chip) and @ad<20010104 and solder and core	USPAT;	2003/09/17 11:35
	,,,	1 7 2 17 2	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	286	((flip adj chip) and @ad<20010104 and solder and core) and (dip\$4	USPAT;	2003/09/17 13:47
		wave)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1			IBM_TDB	L

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	0.5	T( 11 A ) -1 @-1<20010104 and (asmissandustor is ship	USPAT;	2003/09/17 13:48
-	917	(solder near4 wave) and @ad<20010104 and (semiconductor ic chip	US-PGPUB;	2003/03/17 13.40
		(integrated adj circuit))	EPO; JPO;	
		·	DERWENT;	
			IBM TDB	
	112	((-11	USPAT;	2003/09/17 14:11
-	112	((solder near4 wave) and @ad<20010104 and (semiconductor ic chip	· · ·	2003/09/17 14.11
		(integrated adj circuit))) and core	US-PGPUB; EPO; JPO;	
			, , ,	
	ļ		DERWENT;	
			IBM_TDB	2002/00/17 14:14
-	701	(solder near4 (molten melt\$3 liquid dip\$4)) and @ad<20010104 and core	USPAT;	2003/09/17 14:14
		and (bump ball)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0000/00/15 14 14
-	179	(solder near4 (molten melt\$3 liquid dip\$4)) and @ad<20010104 and	USPAT;	2003/09/17 14:14
		(solder near4 core) and (bump ball)	US-PGPUB;	
			EPO; JPO;	
ļ			DERWENT;	
			IBM_TDB	
-	137	((solder near4 (molten melt\$3 liquid dip\$4)) and @ad<20010104 and	USPAT;	2003/09/17 14:15
		(solder near4 core) and (bump ball)) and (semiconductor IC (integrated	US-PGPUB;	
1		adj circuit) chip die)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	